



1.0Amp Silicon Schottky Barrier Rectifiers

1N581XLB Series

Features

- Low forward voltage drop
- High current capability
- High surge current capability
- High reliability
- Epitaxial construction

Mechanical Data

- Case: DO-41 Molded Plastic.
- Terminals: Axial leads, solderable per MIL-STD-202, Method 208 guaranteed
- Polarity: Color band denotes cathode end.
- Epoxy: UL 94V-0 rate flame retardant
- Mounting position: Any
- Weight: 0.34 grams

Maximum Ratings and Electrical Characteristics

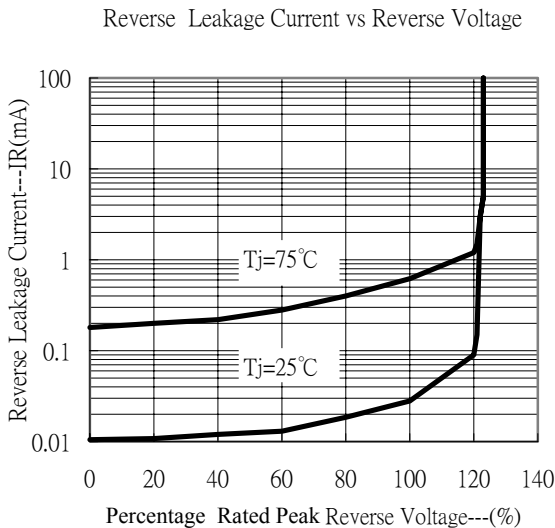
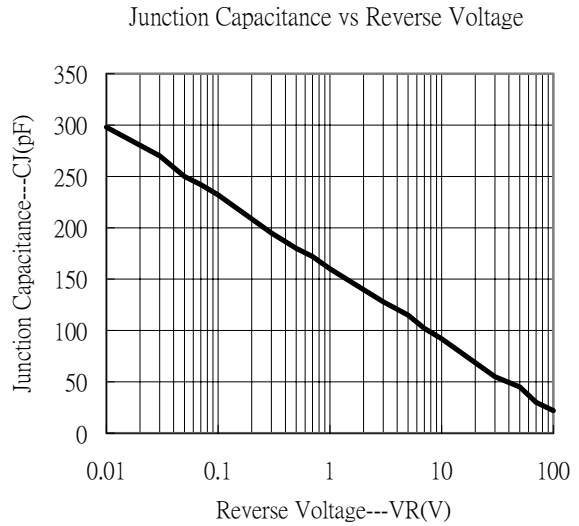
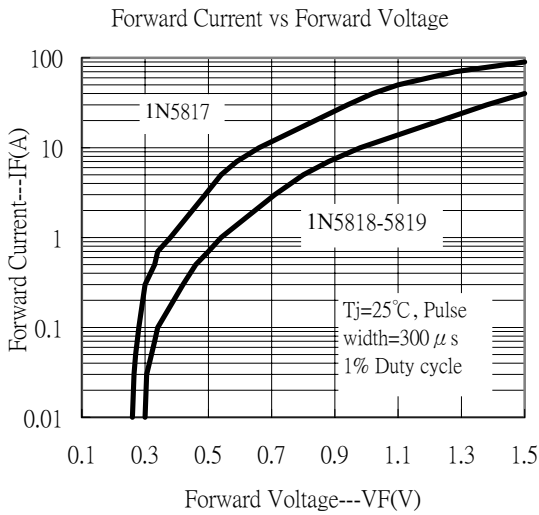
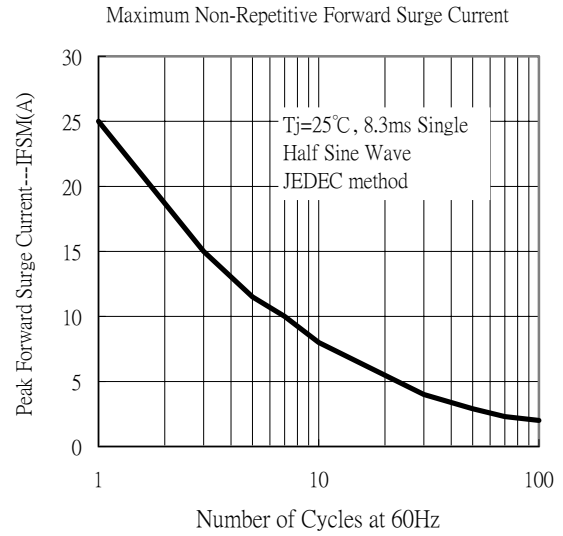
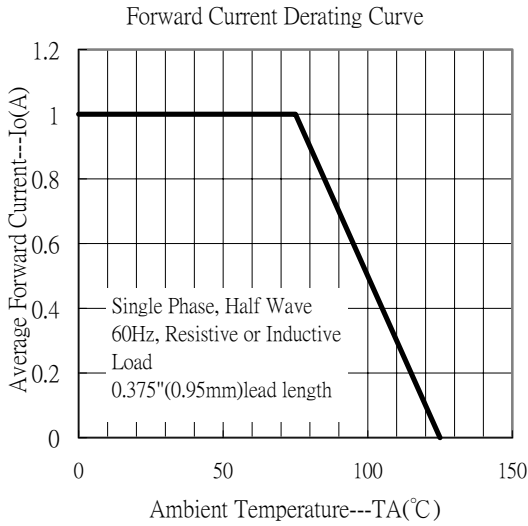
Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Type Number	1N5817	1N5818	1N5819	Units
Maximum Recurrent Peak Reverse Voltage	20	30	40	V
Maximum RMS Voltage	14	21	28	V
Maximum DC Blocking Voltage	20	30	40	V
Maximum Average Forward Rectified Current .375"(9.5mm) lead length at Ta=90°C	1			A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load(JEDEC method)	25			A
Maximum Instantaneous Forward Voltage @ 1.0A	0.45	0.55	0.6	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	1 (@Ta=25°C) 10 (@Ta=100°C)			mA
Typical Junction Capacitance (Note 1)	110			pF
Typical thermal resistance(Note 2)	80			°C/W
Operating Temperature Range Tj	-65 to +125			°C
Storage Temperature Range Tstg	-65 to +150			°C

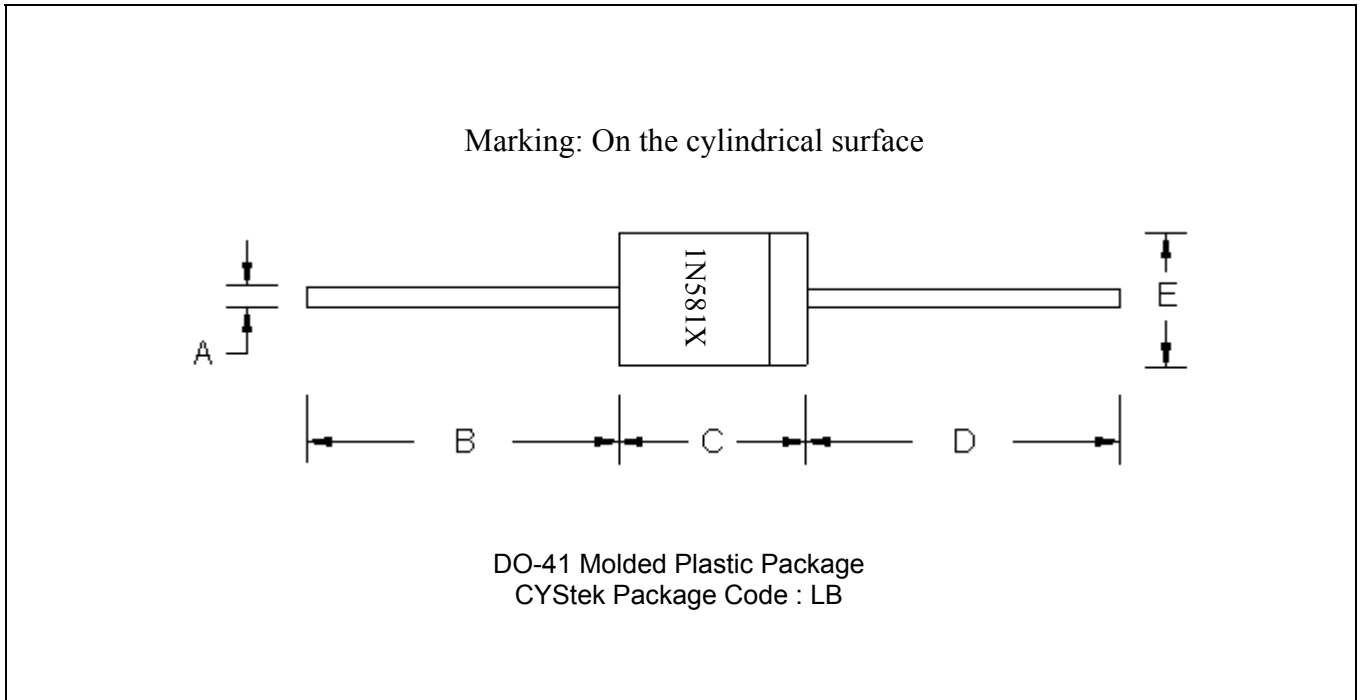
Notes : 1. Measured at 1 MHz and applied reverse voltage of 4.0Volts

2. Thermal resistance from junction to ambient, vertical PCB mounting, 0.5"(12.7mm) lead length.

Characteristic Curves



DO-41 Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0280	0.0340	0.71	0.86	D	1.0000	-	25.40	-
B	1.0000	-	25.40	-	E	0.0800	0.1070	2.00	2.70
C	0.1600	0.2050	4.10	5.20					

Notes : 1. Controlling dimension : millimeters.
 2. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3. If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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